TOSHIBA Power Transistor Module Silicon NPN Epitaxial Type (Four Darlington Power Transistor in One)

MP4301

High Power Switching Applications

Hammer Drive, Pulse Motor Drive and Inductive Load Switching

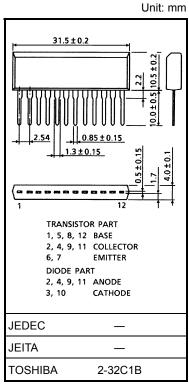
- Small package by full molding (SIP 12 pin)
- $\bullet \quad \hbox{High collector power dissipation (4 devices operation)}$

 $: P_T = 4.4 \text{ W (Ta} = 25^{\circ}\text{C)}$

- High collector current: IC(DC) = 3 A (max)
- High DC current gain: $h_{FE} = 2000$ (min) ($V_{CE} = 2$ V, $I_{C} = 1.5$ A)

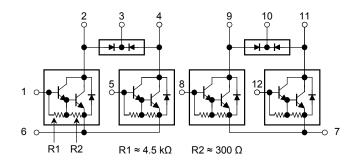
Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Collector-base voltage		V _{CBO}	120	V	
Collector-emitter voltag	Collector-emitter voltage		100	V	
Emitter-base voltage		V _{EBO}	6	V	
Collector current	DC	I _C	3	Α	
Collector current	Pulse	I _{CP}	6	A	
Continuous base currer	Continuous base current		0.5	Α	
Collector power dissipation (1-device operation)		P _C	2.2	W	
Collector power dissipation (4-device operation)		P _T	4.4	W	
Junction temperature		Tj	150	°C	
Storage temperature range		T _{stg}	-55 to 150	°C	

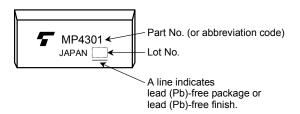


Weight: 3.9 g (typ.)

Array Configuration



Marking



Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance from junction to ambient	ΣR _{th (j-a)}	28.4	°C/W	
(4-device operation, Ta = 25°C)	()/			
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for 10 s)				

Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO}	V _{CB} = 120 V, I _E = 0 A	_	_	10	μA
Collector cut-off cu	rrent	I _{CEO}	V _{CE} = 100 V, I _B = 0 A	_	_	10	μA
Emitter cut-off curre	ent	I _{EBO}	V _{EB} = 6 V, I _C = 0 A	0.5	_	2.5	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = 1 mA, I _E = 0 A	120	_	_	V
Collector-emitter br	reakdown voltage	V (BR) CEO	I _C = 10 mA, I _B = 0 A	100	_	_	V
DC current gain		h _{FE (1)}	V _{CE} = 2 V, I _C = 1.5 A	2000	_	15000	_
DC current gain		h _{FE (2)}	V _{CE} = 2 V, I _C = 3 A	1000	_	_	
Saturation voltage -	Collector-emitter	V _{CE (sat)}	I _C = 1.5 A, I _B = 3 mA	_	_	1.5	V
	Base-emitter	V _{BE (sat)}	I _C = 1.5 A, I _B = 3 mA	_	_	2.0	
Transition frequence	cy	f _T	V _{CE} = 2 V, I _C = 0.5 A	_	60	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = 10 V, I _E = 0 A, f = 1 MHz	_	30	_	pF
Switching time Storage time Fall time	t _{on}	Output	_	0.3	_		
	Storage time	t _{stg}	$I_{B1} = -I_{B2} = 3 \text{ mA, duty cycle} \le 1\%$	ı	2.0	_	μs
	Fall time	t _f		_	0.4	_	

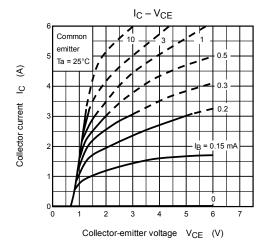
Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

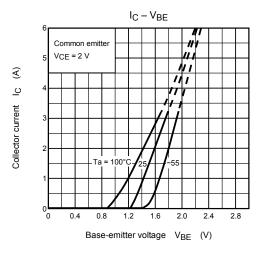
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Maximum forward current	I _{FM}	_	_	_	3	Α
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	6	Α
Forward voltage	V _F	I _F = 1 A, I _B = 0 A	_	1.2	1.8	٧
Forward voltage	t _{rr}	$I_F = 3 \text{ A}, V_{BE} = -3 \text{ V}, dI_F/dt = -50 \text{ A/}\mu\text{s}$	_	1.0	_	μs
Reverse recovery charge	Q _{rr}		_	5	_	μC

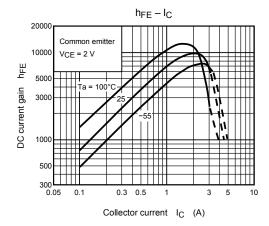
Flyback-Diode Ratings and Characteristics (Ta = 25°C)

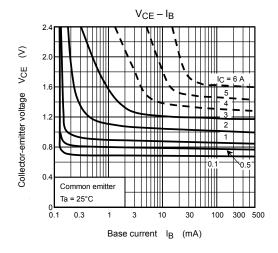
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Maximum forward current	I _{FM}	_	_	_	3	Α
Reverse current	I _R	V _R = 120 V	_	_	0.4	μΑ
Reverse voltage	V_{R}	I _R = 100 μA	120	_	_	V
Forward voltage	V _F	I _F = 0.5 A	_	_	1.8	V

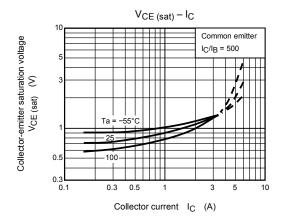
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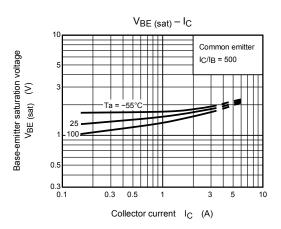


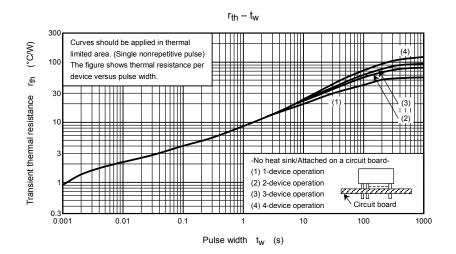


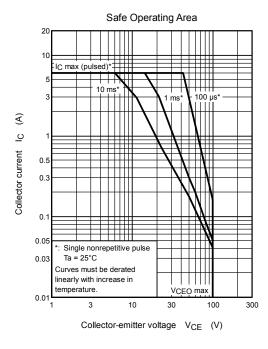


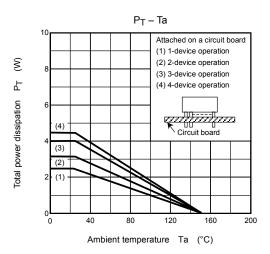


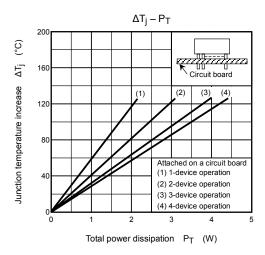












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